Material Data Sheet

Infineon Technologies Bipolar GmbH & Co. KG



Product family name	**PowerBLOCK 50mm DZ**
Date	**19.09.2023**
Revision	**5**

Construction element	*Material group*	*Materials*	*CAS-Nr.* *if applicable*	*Average mass [%]**	*Sum [%]*	*Traces*	*Comment*
Semiconductor inluding leads, solder and ceramics	other metals	Molybdenum	7439-98-7	3,1%	4,7%		Molybdenum galv. Ruthenium; Molybdenum galv. or PVD Silver; Molybdenum galv. or PVD AM (Gold/ Chromium)
		Chromium	7440-47-3			X	
		Nickel	7440-02-0			X	
		Ruthenium	7440-18-8			X	
	nonferrous metals	Copper	7440-50-8	1,3%			Copper galv. Silver Copper galv. Nickel
	nobel metal	Silver	7440-22-4			X	
	Semi metals	Silicon	7440-21-3	0,2%			silicon chip doped with very small amounts of elements such as boron, arsenic or phosphorus
	Aluminium alloy	Aluminium	7429-90-5			X	
		Silicon	7440-21-3			X	
	Polymers	Silicone rubber	9002-84-0	0,1%			
Package including cover, gel and baseplate	nonferrous metals	Copper	7440-50-8	64,6%	95,3%		Copper galv. Silver Copper galv. Nickel
	Inorganic materials, ceramics	ALN		1,4%			
		Al203				X	
	Iron alloy	Iron	7439-89-6	13,9%			
		Zinc				X	Iron galv. Zinc
		Nickel	7440-02-0			X	Iron galv.Nickel
	Polymers	Epoxide		2,9%			
		Silicon	7440-21-3	0,1%			
		PPS		12,3%			Classification R22: HL3 R23: HL3
				Sum in total:	**100%**		

Weight range of product family **	**760 g - 910 g**
Fluctuation margin	+/- 5%

*) related to component weight
**) Weight of particular product, see technical product information

1) Only substances,

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